

File View Edit Tools Window Help

Pending

Active

- L1: (421) multi-layer\$2 near interconnect
- L2: (445) multi-layer\$2 near interconnect or ((multi adj layer) near interconnect)
- L3: (69) 2 and (conduct\$3 and ceramic and dielectric)
- L4: (2) 2 and (conduct\$3 and (ceramic near layer) and (dielectric near layer))
- L5: (848) multi-layer\$2 near interconnect or ((multi adj layer) near interconnect) or multilayer
- L6: (192) 5 and (conduct\$3 and ceramic and dielectric)
- L7: (185) 5 and (conduct\$3 and ceramic and dielectric and substrate)
- L8: (20) 5 and (patterned near conduct\$3 and ceramic and dielectric and substrate)
- L9: (19) 5 and (conduct\$3 near pad\$1 and ceramic and dielectric and substrate)
- L10: (22) 5 and (ceramic near layer and dielectric)
- L11: (17) 5 and (ceramic near layer and dielectric near layer)
- L12: (12) 5 and (ceramic near layer and dielectric near layer and organic)

Failed

- (0) 6 and (packag\$3 and (organic near dielectric) and (ceramic near dielectric))
- (0) ((integrated adj circuit) near carrier) or (IC near carrier))

Saved

- (534) (hybrid adj integrated adj circuit or hybrid adj IC) near substrate
- (61) ((hybrid adj integrated adj circuit or hybrid adj IC) near substrate) and (conductive and d
- (41) ((hybrid adj integrated adj circuit or hybrid adj IC) near substrate) and (conductive and d
- (60) ((hybrid adj integrated adj circuit or hybrid adj IC) near substrate) and (dielectric and c...
- (118) ((hybrid adj integrated adj circuit or hybrid adj IC) near substrate) and (packag\$3)
- (3355) (hybrid adj integrated adj circuit or hybrid adj IC) and substrate
- (178) ((hybrid adj integrated adj circuit or hybrid adj IC) and substrate) and (packag\$3 and di
- (0) ((hybrid adj integrated adj circuit or hybrid adj IC) and substrate) and (packag\$3 and (org
- (3) ((hybrid adj integrated adj circuit or hybrid adj IC) and substrate) and (packag\$3 and (org
- (5) ((hybrid adj integrated adj circuit or hybrid adj IC) and substrate) and ((organic near diel.
- (350) ((hybrid adj integrated adj circuit or hybrid adj IC) and substrate) and (dielectric and c...

DB: ☐ Plurals

Default opera ☒ Highlight all hit terms initially

5 and (ceramic near layer and dielectric near layer and organic)

ABR A S Int Text HTML

	U	I	Document ID	Issue Date	Pages	Title	Current OP	Current XRef
1	<input type="checkbox"/>	<input type="checkbox"/>	US 20030155590 A1	20030821	24	Semiconductor device	257/259	257/E23.15
2	<input type="checkbox"/>	<input type="checkbox"/>	US 5976710 A	19991102	8	Low TCE polyimides as improved insulator in multilayer interconnect structures	428/620	257/40, 257/684,
3	<input type="checkbox"/>	<input type="checkbox"/>	US 5780375 A	19980714	6	Thick film composition for modifying the electrical properties of a dielectric layer	501/137	361/320, 361/321.1,
4	<input type="checkbox"/>	<input type="checkbox"/>	US 5737458 A	19980407	20	Optical light pipe and microwave waveguide interconnects in multichip modules formed	385/15	385/130, 385/52
5	<input type="checkbox"/>	<input type="checkbox"/>	US 5562838 A	19961008	20	Optical light pipe and microwave waveguide interconnects in multichip modules formed	216/24	216/33, 216/39
6	<input type="checkbox"/>	<input type="checkbox"/>	US 5525190 A	19960611	20	Optical light pipe and microwave waveguide interconnects in multichip modules formed	385/133	216/23, 216/24,
7	<input type="checkbox"/>	<input type="checkbox"/>	US 5422223 A	19950606	8	Silicon-containing positive resist and use in multilayer metal structures	430/190	430/166, 430/192,
8	<input type="checkbox"/>	<input type="checkbox"/>	US 5268533 A	19931207	8	Pre-stressed laminated lid for electronic circuit package	174/52.4	257/704, 257/E23.181,
9	<input type="checkbox"/>	<input type="checkbox"/>	US 5232548 A	19930803	8	Discrete fabrication of multi-layer thin film, wiring structures	216/18	216/20, 29/852,
10	<input type="checkbox"/>	<input type="checkbox"/>	US 5202153 A	19930413	17	Method for making thick film/solder joints	427/125	427/123, 427/126.2,
11	<input type="checkbox"/>	<input type="checkbox"/>	US 5080958 A	19920114	7	Multilayer interconnects	428/209	156/60, 361/748,

HTML Details HTML